

## **AMENDMENTS TO THE CLAIMS**

**Claim 1 (Currently Amended)** A method of manufacturing a multi-layer circuit board in which a core circuit board having a circuit pattern thereon and a prepreg sheet having a through-hole filled with conductive paste are laminated, the method comprising:

forming a laminated structure from (i) so that a laminated member including formed of the core circuit board and the prepreg sheet and (ii) a pair of lamination plates, the laminated member being is sandwiched between a the pair of lamination plates, and; and

applying heat and pressure to the laminated structure,

wherein, the lamination plate is selected so as to have a thermal expansion coefficient of the pair of lamination plates is equivalent to a thermal expansion coefficient of the core circuit board.

**Claim 2 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the prepreg sheet includes contains a base and a two resin layers being layer impregnated with the base, and wherein a total thickness of the two resin layers layer formed on both surfaces of the base is at least 20 μm in total thickness.

**Claim 3 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the core circuit board has includes at least four or more layers.

**Claim 4 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the core circuit board is not less than one times a thickness of time as thick as the prepreg sheet.

**Claim 5 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the laminated member further includes a layer of ~~contains~~ metal foil on both surfaces thereof, each metal layer being sandwiched between the pair of lamination plates.

**Claim 6 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the laminated member is formed from ~~in a manner that~~ the core circuit board and the prepreg sheet ~~are~~ being alternately laminated, so as to have two or more layers.

**Claim 7 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein:

a buffer material is disposed at an outside of the laminated structure;  
the laminated structure is placed on a carrying plate;  
the laminated structure undergoes heat and pressure through the buffer material and the carrying plate; and  
a thermal expansion coefficient of the carrying plate equals ~~to a~~ the thermal expansion coefficient of the pair of lamination plates ~~plate~~.

**Claim 8 (Currently Amended)** The method of manufacturing a multi-layer circuit board of

Claim 1, wherein:

a buffer material is disposed at an outside of the laminated structure;

the laminated structure is placed on a carrying plate;

the laminated structure undergoes heat and pressure through the buffer material and the carrying plate; and

the buffer material is formed of a material capable of accommodating a difference in the thermal expansion of between the pair of lamination plates plate and a thermal expansion of the carrying plate.

**Claim 9 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the prepreg sheet includes contains a base impregnated with a resin and, wherein a layer of the resin is formed on both surfaces of the base.

**Claim 10 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1, wherein the prepreg sheet is a B-staged prepreg in which a woven fabric base is impregnated with a thermosetting resin.

**Claim 11 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 1 further including:

measuring the thermal expansion coefficient of the core circuit board; and

selecting the pair of lamination plates plate whose such that the thermal expansion coefficient of the pair of lamination plates is equivalent to the measured thermal expansion

coefficient of the core circuit board.

**Claim 12 (Currently Amended)** A method of manufacturing a multi-layer circuit board in which a core circuit board having a circuit pattern thereon and a prepreg sheet having a through-hole filled with conductive paste are laminated, the method comprising:

forming a laminated structure from (i) a laminated member including the core circuit board and the prepreg sheet and (ii) a pair of lamination plates, the laminated member being is sandwiched between the pair of lamination plates;

applying heat and pressure to the laminated structure;

measuring the thermal expansion coefficient of the core circuit board having a predetermined circuit pattern; and

selecting the pair of a lamination plates such that the plate whose thermal expansion coefficient of the pair of lamination plates is equivalent to the measured thermal expansion coefficient of the core circuit board.

**Claim 13 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 12, wherein the measuring of the thermal expansion coefficient of the core circuit board includes measuring is for measuring the thermal expansion coefficient of the core circuit board (i) at least two or more positions of the circuit pattern on the core circuit board and (ii) in a range from room temperature to a heat pressing temperature, the measuring being conducted by using a thermo-mechanical measurement apparatus.

**Claim 14 (Currently Amended)** The method of manufacturing a multi-layer circuit board of Claim 12, wherein:

the measuring of the thermal expansion coefficient of the core circuit includes-  
~~coefficient measuring is for measuring~~ the thermal expansion coefficient of the core circuit board at two or more positions; and; and

the method further ~~comprising:~~ comprises:  
calculating an average value of the thermal expansion coefficient of the core circuit board according to the measurement carried out at the two or more positions; and  
selecting the pair of lamination plates such that the plate whose thermal expansion coefficient of the pair of lamination plates is equivalent to the calculated average value of the thermal expansion coefficient.